

ATTORNEY DOCKET NO: M&M-067-USA-P**DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR FORMING SOLDER-RESIST FILM

the specification of which is ☐ attached and/or ☒ was filed on July 31, 2003 as Application Serial No. 10/630,858 and was amended on (if applicable)
☐ international (PCT) application No. filed and as amended on (if any).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE OF FILING	PRIORITY CLAIMED UNDER 35 U.S.C. 119
JAPAN	224827/2002	August 1, 2002	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO

☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION NUMBER	DATE OF FILING	STATUS (Patented, Pending, Abandoned)

I hereby appoint the following attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Law Offices of Townsend & Banta: Donald E. Townsend, Registration No. 22,069; Teresa J. Banta, Registration No. 34,543; and ..Donald E. Townsend, Jr., Reg. No. 43,198.....
Please address all correspondence to the Law Offices of Townsend & Banta, Suite 500, 1225 Eye Street, N.W., Washington, D.C. 20005

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF SOLE OR FIRST INVENTOR Keiichi OKAJIMA		INVENTOR'S SIGNATURE <i>Keiichi Okajima</i>	DATE July 28, 2003
RESIDENCE 1-10-22-704, Chuo, Joto-ku, Osaka-city, Osaka 536-0005 JAPAN		CITIZENSHIP JAPAN	
POST OFFICE ADDRESS Same as Residence			
FULL NAME OF SECOND JOINT INVENTOR, IF ANY Hiroshi ODA		INVENTOR'S SIGNATURE <i>Hiroshi Oda</i>	DATE July 28, 2003
RESIDENCE 7-2-301, Asahigaoka, Toyonaka-city, Osaka 561-0085 JAPAN		CITIZENSHIP JAPAN	
POST OFFICE ADDRESS Same as Residence			

Listing of Inventors Continued on Page 2 hereof. ☒ Yes ☐ No

Listing of Inventors Continued from Page 1 of Declaration and Power of Attorney for invention entitled:

METHOD FOR FORMING SOLDER-RESIST FILM

FULL NAME OF THIRD JOINT INVENTOR, IF ANY Takahiro NAKANO		INVENTOR'S SIGNATURE <i>Takahiro NAKANO</i>	DATE July, 28, 2003
RESIDENCE 1-43-918, Shimeien, Ibaraki-city, Osaka 567-0045 JAPAN		CITIZENSHIP JAPAN	
POST OFFICE ADDRESS Same as Residence			
FULL NAME OF FOURTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF FIFTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF SIXTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF SEVENTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF EIGHTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF NINTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			
FULL NAME OF TENTH JOINT INVENTOR, IF ANY		INVENTOR'S SIGNATURE	DATE
RESIDENCE		CITIZENSHIP	
POST OFFICE ADDRESS			